

# DSK5J01×0L

## Silicon N-channel Junction FET

For low frequency amplification / For piezoelectric sensor  
DSK2J01 in SMini3 type package

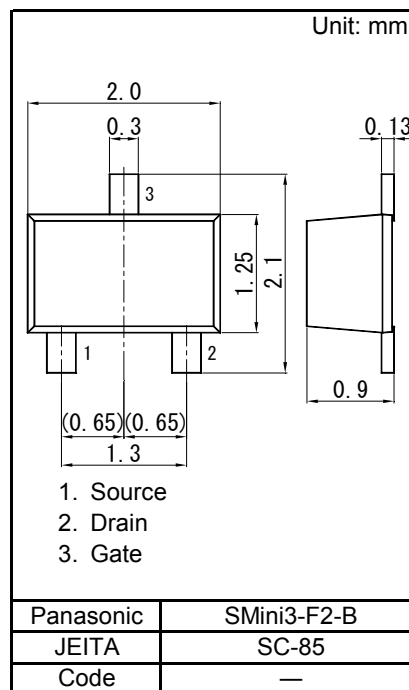
■ Features

- High gate-drain Voltage(Source open)VGDO
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: B6

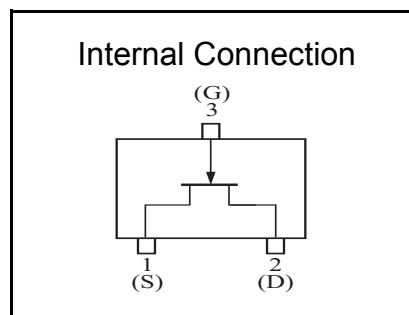
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Gate-drain voltage (Source short)	VGDS	-55	V
Drain current	ID	30	mA
Gate current	IG	10	mA
Power dissipation	PD	150	mW
Channel temperature	Tch	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain voltage (Source short)	VGDS	IG = -100 μA, VDS = 0	-55			V
Drain current *1	IDSS	VDS = 10 V, VGS = 0	1.0		12.0	mA
Gate-source cutoff current	IGSS	VGS = -30 V, VDS = 0			-10	nA
Gate-source cutoff voltage	VGSC	VDS = 10 V, ID = 10 μA			-5	V
Forward transfer admittance	Yfs	VDS = 10 V, ID = 5 mA, f = 1 kHz	2.5	7.5		mS
Small-signal short-circuit input capacitance	Ciss	VDS = 10 V, VGS = 0, f = 1 MHz		6.0		pF
Small-signal reverse transfer capacitance	Crss			2.5		pF

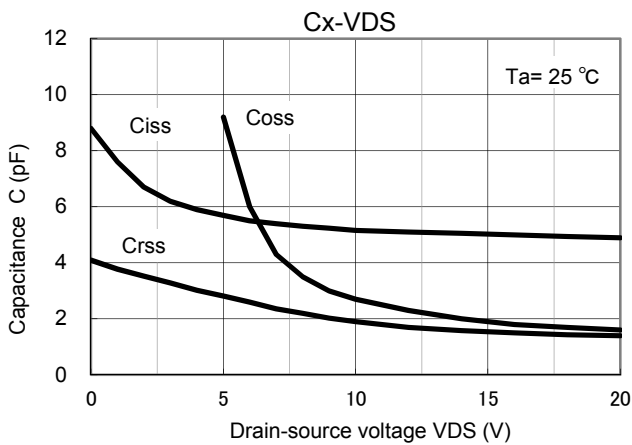
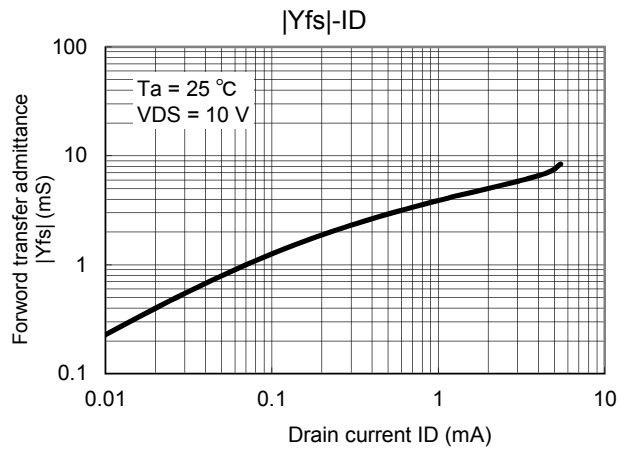
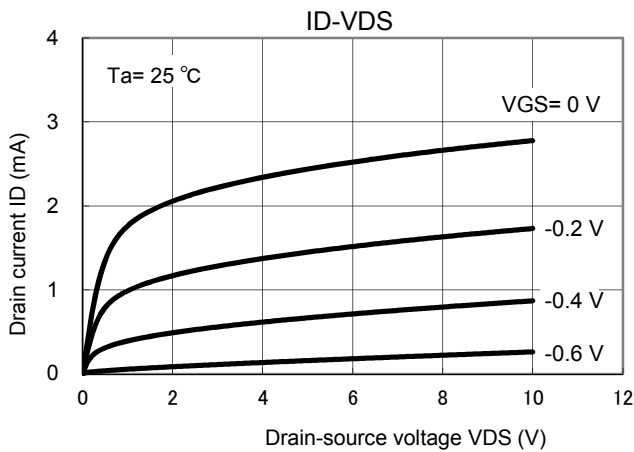
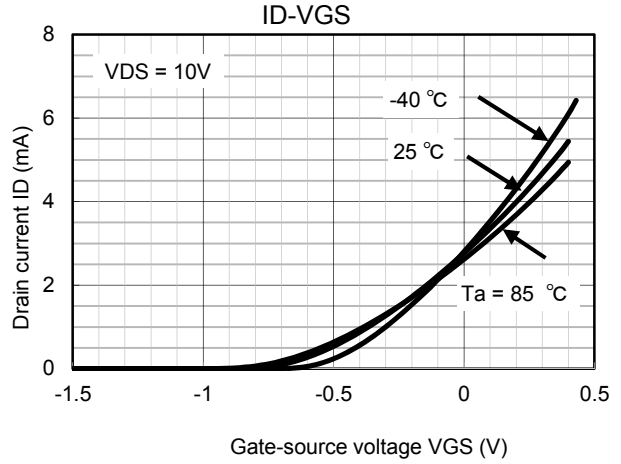
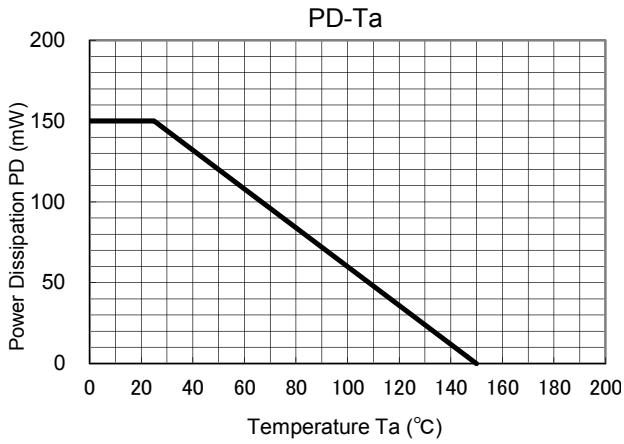
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Rank classification

Code	P	Q	R
Rank	P	Q	R
IDSS (mA)	1.0 to 3.0	2.0 to 6.5	5.0 to 12.0
Marking symbol	B6P	B6Q	B6R



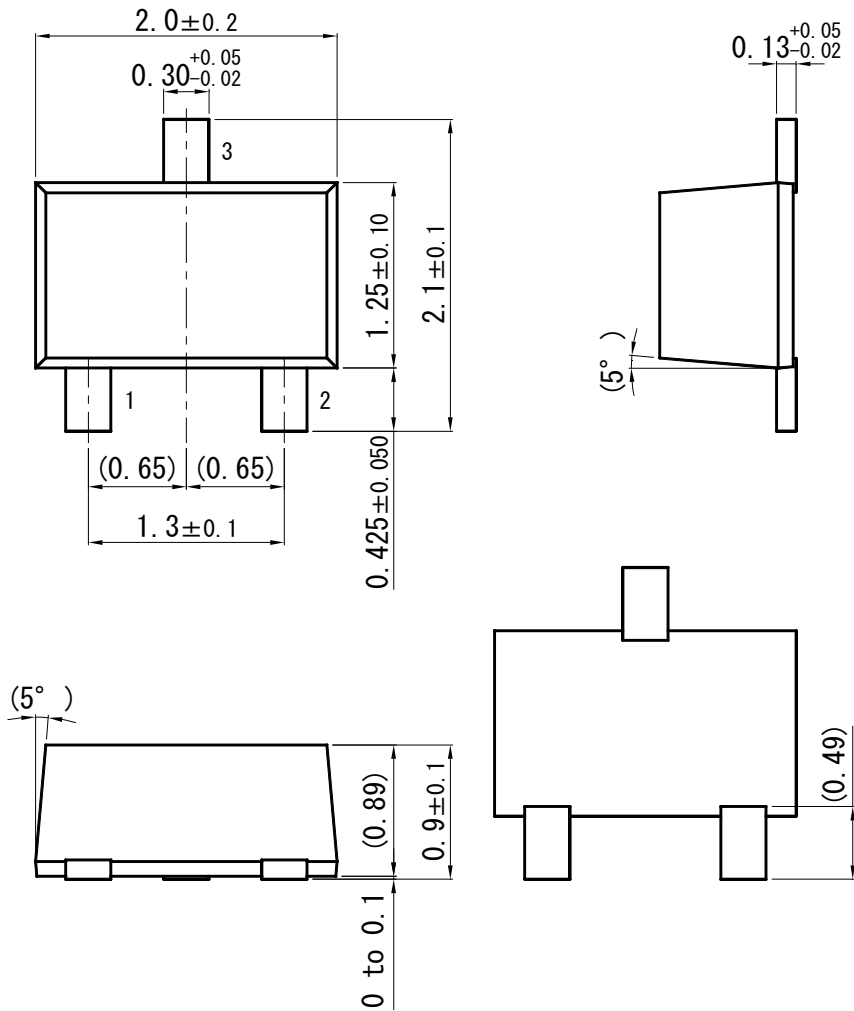
Technical Data ( reference )



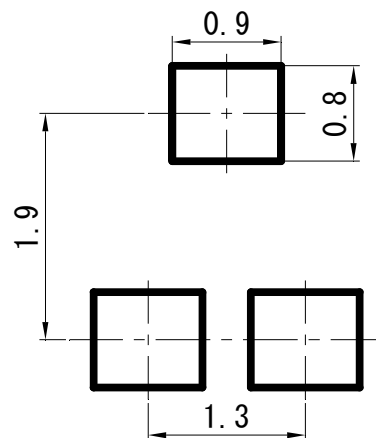


### SMini3-F2-B

Unit: mm



#### ■ Land Pattern (Reference) (Unit: mm)



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